

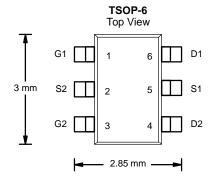
## NDC7003P-VB Datasheet Dual P-Channel 60-V (D-S) MOSFET

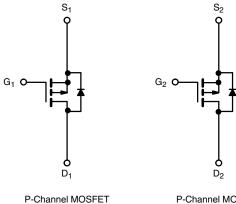
PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) Typ.	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (TYP.)			
-60	0.070 at V <sub>GS</sub> = -10 V	-4.5	10.1 nC			
-00	0.085 at $V_{GS}$ = -4.5 V	-4.0	10.1110			

### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET •
- Compliant to RoHS Directive 2002/95/EC •







P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS (TA</b>	= 25 °C, unless other	wise noted)		
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V <sub>DS</sub>	-60	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		-4.5	
Continuous Drain Current (T 150 °C)	T <sub>C</sub> = 70 °C		-4.0	
Continuous Drain Current ( $T_J = 150 \ ^{\circ}C$ )	T <sub>A</sub> = 25 °C	I <sub>D</sub>	-3.5 <sup>a,b</sup>	
	T <sub>A</sub> = 70 °C	]	-3.0 <sup>a,b</sup>	^
Pulsed Drain Current (t = 100 µs)	I <sub>DM</sub>	-20	Α	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		-3.9	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	-2.1 <sup>a,b</sup>	
Avalanche Current		I <sub>AS</sub>	-15	
Single-Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	11.25	mJ
	T <sub>C</sub> = 25 °C		4.2	
Maximum Dawar Dissipation	T <sub>C</sub> = 70 °C		2.7	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2 <sup>a,b</sup>	vv
	T <sub>A</sub> = 70 °C		1.3 <sup>a,b</sup>	
Operating Junction and Storage Temperature Rang	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C	

THERMAL RESISTANCE RATINGS							
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT			
Maximum junction-to-ambient <sup>a</sup>	t ≤ 5 s	R <sub>thJA</sub>	100	130	°C/W		
Maximum junction-to-case (drain)	Steady state	R <sub>thJF</sub>	60	75	- C/W		

#### Notes

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

- c. Maximum under steady state conditions is 110 °C/W.
- d. Based on  $T_C = 25$  °C.

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static			1	1	1	1	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = -250 \mu\text{A}$	-60	-	-	V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_J$	L 050 A	-	-6.7	-	mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- I <sub>D</sub> = -250 μΑ	-	4.3	-		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$	-1	-	-3	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	± 100	nA	
	1	$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	-1	μA	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$	-	-	-5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	-30	-	-	А	
Duain Course On Otata Desistance 3	D	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -3.5 A	-	0.070	-	-	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -2.8 A	-	0.085	-	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = -30 \text{ V}, \text{ I}_{D} = -3.5 \text{ A}$	-	11	-	S	
Dynamic <sup>b</sup>		•					
Input Capacitance	C <sub>iss</sub>		-	832	-	pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$	-	88	-		
Reverse Transfer Capacitance	C <sub>rss</sub>		-	63	-		
Total Gate Charge	Qg	$V_{DS} = -30$ V, $V_{GS} = -10$ V, $I_D = -3.5$ A	-	20	30	nC	
			-	10.1	15.2		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -3.5 \text{ A}$	-	3.3	-		
Gate-Drain Charge	Q <sub>gd</sub>		-	3.9	-		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	1.8	9	18	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>		-	8	16	-	
Rise Time	t <sub>r</sub>	$V_{DD}$ = -30 V, $R_L$ = 10.7 $\Omega$	-	6	12		
Turn-Off DelayTime	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ -2.8 A, $\text{V}_\text{GEN}$ = -10 V, $\text{R}_\text{g}$ = 1 $\Omega$	-	35	53		
Fall Time	t <sub>f</sub>		-	16	24		
Turn-On Delay Time	t <sub>d(on)</sub>		-	40	60	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = -30 \text{ V}, \text{ R}_{L} = 10.7 \Omega$	-	28	42	-	
Turn-Off DelayTime	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ -2.8 A, $\text{V}_\text{GEN}$ = -4.5 V, $\text{R}_\text{g}$ = 1 $\Omega$	-	31	47		
Fall Time	t <sub>f</sub>		-	15	23		
Drain-Source Body Diode Characterist	ics						
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	-3.5	٨	
Pulse Diode Forward Current (t = 100 µs)	I <sub>SM</sub>		-	-	-20	A	
Body Diode Voltage	V <sub>SD</sub>	$I_{\rm S}$ = -2.8 A, $V_{\rm GS}$ = 0 V	-	-0.85	-1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>		-	32	48	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = -2.8 A, dl/dt = 100 A/μs,	-	45	68	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$T_{\rm J} = 25 \ ^{\circ}{\rm C}$		24	-		
Reverse Recovery Rise Time t <sub>b</sub>		1	-	8	-	ns	

#### Notes

a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$ 

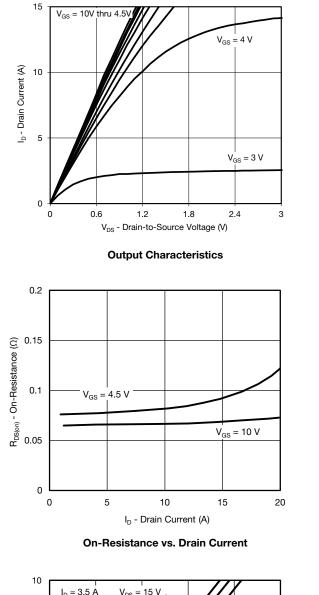
b. Guaranteed by design, not subject to production testing.

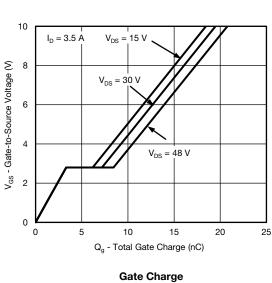
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

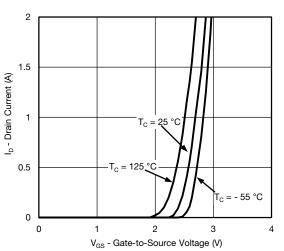
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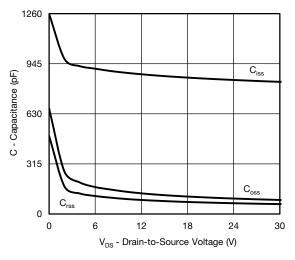




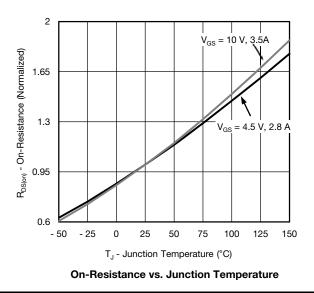




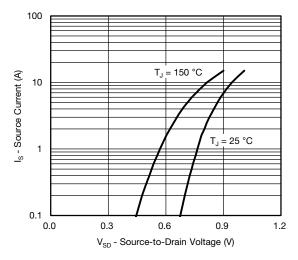
Transfer Characteristics



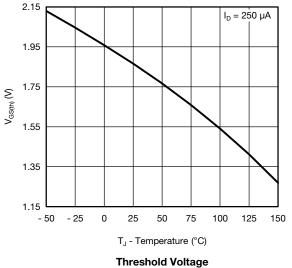




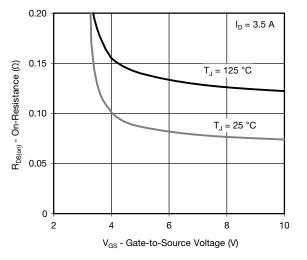




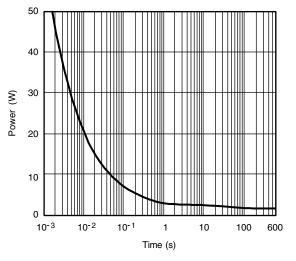
Source-Drain Diode Forward Voltage



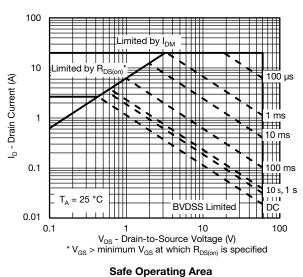




**On-Resistance vs. Gate-to-Source Voltage** 

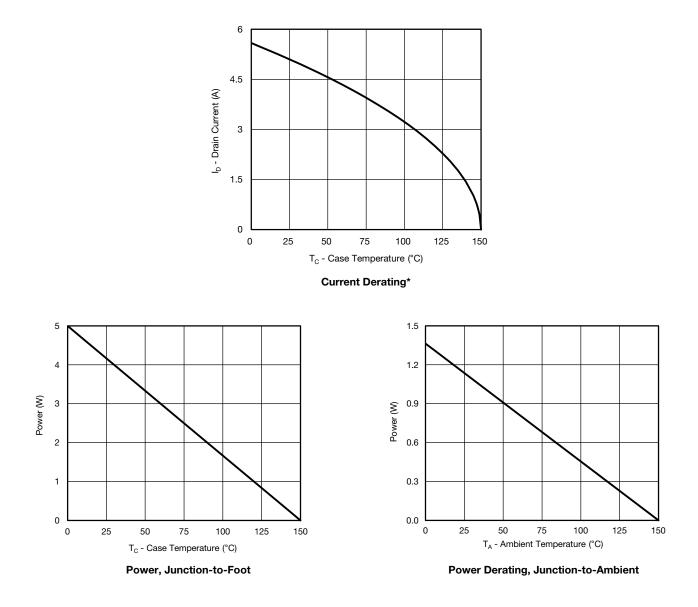


Single Pulse Power, Junction-to-Ambient



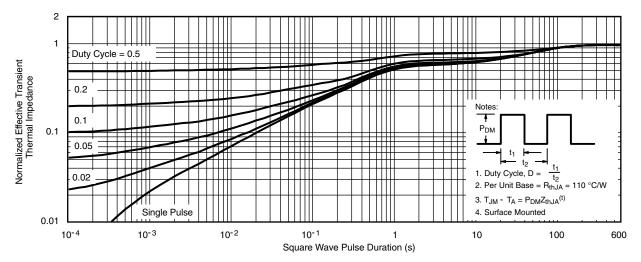
服务热线:400-655-8788

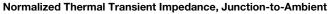


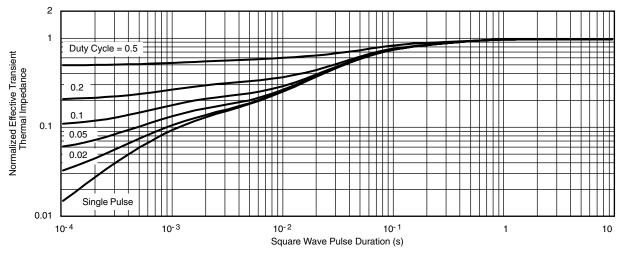


\* The power dissipation  $P_D$  is based on  $T_{J (max.)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





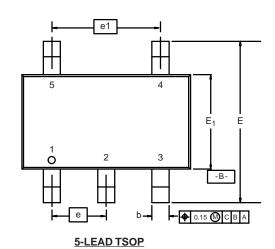


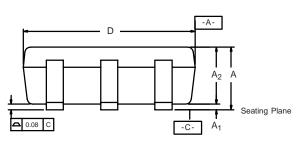


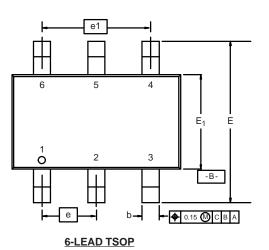
Normalized Thermal Transient Impedance, Junction-to-Foot

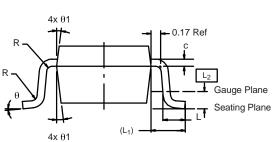


TSOP: 5/6–LEAD JEDEC Part Number: MO-193C





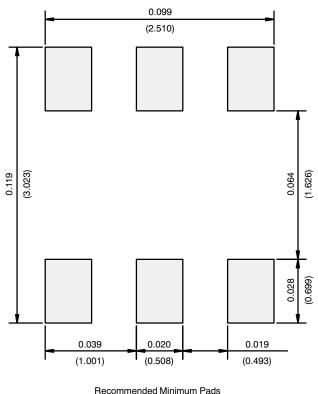




	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A <sub>1</sub>	0.01	-	0.10	0.0004	-	0.004	
A <sub>2</sub>	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
E	2.70	2.85	2.98	0.106	0.112	0.117	
E <sub>1</sub>	1.55	1.65	1.70	0.061	0.065	0.067	
е	0.95 BSC			0.0374 BSC			
e <sub>1</sub>	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L <sub>1</sub>		0.60 Ref		0.024 Ref			
L <sub>2</sub>	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ1	7° Nom			7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							



### **RECOMMENDED MINIMUM PADS FOR TSOP-6**



Recommended Minimum Pads Dimensions in Inches/(mm)



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